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PATENTS ONLY

FORM PTO-1595
(Rev. 10/02)

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 070679-0121

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto.

6-30-06

1. Name of Conveying Party(ies):
Jae-II KIM, Jae-Hyuk IM

2. Name and address of receiving party(ies):
Name: HYNIX SEMICONDUCTOR INC.
Address: San 136-1, Ami-ri, Bubal-eub,
Ichon-shi,
Kyoungki-do 467-860, Republic of Korea

112919 U.S. PTO
11/478076

063006

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: June 28, 2006

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
If the document is being filed together with a new application, the execution date of the application is: June 28, 2006

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: MCDERMOTT WILL & EMERY LLP
Internal Address:
Street Address: 600 13th Street, N.W.
City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41) \$40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:
500417

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stephen A. Becker, Registration No. 26,527

June 30, 2006

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet: 3

OMB No. 0651-0027 (exp. 6/30/2005)

07/06/2006 HJANA1 00000126 500417 11478076

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PATENT
REEL: 018063 FRAME: 0610

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

KIM, Jae-II and IM, Jae-Hyuk

who has made a certain new and useful invention, hereby sells, assigns and transfers unto
Hynix Semiconductor Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

TEST DEVICE

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

Kim Jae II

June 28, 2006

Name: **KIM, Jae-II**

INVENTOR

DATE SIGNED

IM Jaehyuk

June 28 , 2006

Name: **IM, Jae-Hyuk**